



# Multicore® Solder Materials

The Multicore® line of solder pastes is designed to meet the rigorous demands of a variety of electronic manufacturing soldering processes. Whether your process requires **long abandon times, wide process windows, or high-speed printing**, Henkel Loctite offers a Multicore® paste to suit your needs.

Henkel Loctite is also breaking new ground in the development of **lead-free** products. As the industry works toward eliminating lead from its products and processes, Henkel Loctite has developed not only the solder technology to meet that need, but will also provide the technical and engineering support crucial to process engineers as they face the unique processing requirements of lead-free operations.



# Multicore® Solder Pastes



## MP200 Solder Paste

### Wide Process Window

DESCRIPTION/APPLICATION	ALLOY	% METAL LOAD	TACK (g./mm <sup>2</sup> )	PRINT SPEED mm/sec.	IPC/J-STD CLASSIFICATION
A high activity, <b>soft, colorless, low residue</b> , no-clean solder paste that exhibits excellent print definition with long open and abandon time capabilities. High activity of the MP200 flux offers excellent wetting to a wide range of surface finishes, and an exceptional reflow process window. Is suitable for fine pitch, high speed printing applications. Pin testable.	SN62/SN63 63S4 (Anti-Tombstoning)	90 90.5	1.1	25 - 200	ROLO

Item number	Product Description	Package size	Item number	Product Description	Package size
<b>M00439</b>	Sn63 MP200 AGS 90	500 Gram Jar	<b>M00443</b>	Sn62 MP200 AGS 90	500 Gram Jar
<b>M00440</b>	Sn63 MP200 AGS 90	700 Gram Semco	<b>M00444</b>	Sn62 MP200 AGS 90	700 Gram Semco
<b>M00441</b>	Sn63 MP200 AGS 90	1300 Gram Semco	<b>M00445</b>	Sn62 MP200 AGS 90	1300 Gram Semco
<b>M00447</b>	Sn63 MP200 AGS 90	20CC EFD Cartridge	<b>M00448</b>	Sn62 MP200 AGS 90	30CC EFD Cartridge
<b>M00505</b>	Sn63 MP200 AGS 90.5	750 Gram Proflow	<b>M00506</b>	Sn62 MP200 AGS 90.5	750 Gram Proflow
<b>M00449</b>	Multi-Tak MP 200 (Rework Flux)	30CC Cartridge	<b>M00479</b>	63S4 MP200 ACP 90	500 Gram Jar
			<b>M00480</b>	63S4 MP200 ACP 90	700 Gram Semco
			<b>M00481</b>	63S4 MP200 ACP 90	1300 Gram Semco

## CR36 No-Clean Solder Paste

### Highest Activity Offering

DESCRIPTION/APPLICATION	ALLOY	% METAL LOAD	TACK (g./mm <sup>2</sup> )	PRINT SPEED mm/sec .	IPC/J-STD CLASSIFICATION
A <b>high activity, colorless residue</b> , no-clean solder paste. CR36 exhibits good abandon time, long stencil life, and minimal hot slump. It has excellent wetting to a wide range of surface finishes. The activity of CR36 gives it an exceptional reflow process window, making it suitable for both volume and high mix manufacturing.	SN62/SN63	89.5	1.3 - 1.6	20 - 200	ROLO

Item number	Product Description	Package size
<b>M00086</b>	Sn63 CR36 AGS 89.5	500 Gram Jar
<b>M00219</b>	Sn63 CR36 AGS 89.5	500 Gram Semco



## LF320 Lead Free Paste

### Wide Process Window

DESCRIPTION/APPLICATION	ALLOY	% METAL LOAD	TACK (g./mm <sup>2</sup> )	PRINT SPEED mm/sec .	IPC/J-STD CLASSIFICATION
A <b>no-clean flux system</b> specially formulated for Pb-free alloys. High temperature tolerance and wide printing capability. 96SC alloy (Sn 95.5, Ag 3.5, Cu 0.7%) reflows at 217°C.	96SC	88	1.2	20-150	ROMO

Item number	Product Description	Package size
<b>M00501</b>	96SC LF320 AGS88	500 Gram Jar
<b>M00502</b>	96SC LF320 AGS88	600 Gram Semco



## WS200 Water Wash Paste

DESCRIPTION/APPLICATION	ALLOY	% METAL LOAD	TACK (g./mm <sup>2</sup> )	PRINT SPEED mm/sec .	IPC/J-STD CLASSIFICATION
High performance water washable solder paste. Residues are readily removed with DI water, without the need for a saponifier. WS200 has good open time with excellent print definition and soldering activity.	SN62/SN63	90.5	0.8	25-100	ORH1

Item number	Product Description	Package size	Item number	Product Description	Package size
<b>M00486</b>	Sn63 WS200 AGS 90.5	500 Gram Jar	<b>M00488</b>	Sn62 WS200 AGS 90.5	500 Gram Jar
<b>M00487</b>	Sn63 WS200 AGS 90.5	700 Gram Semco	<b>M00489</b>	Sn62 WS200 AGS 90.5	700 Gram Semco
<b>M00508</b>	Sn63 WS200 AGS 90.5	1300 Gram Semco	<b>M00509</b>	Sn62 WS200 AGS 90.5	1300 Gram Semco

# Multicore® No-Clean Fluxes



## X32-10 No-Clean Flux

### Clear Residue-Wide Process Window

DESCRIPTION/APPLICATION	% SOLIDS	% HALIDES	ACID VALUE	IPC CLASS	APPLICATION
A general purpose halide-free low solids flux which leaves clean, dry boards after wave soldering. Suitable for foam and spray flux application systems.	2.2	Zero	15.3	REMO	Spray/Foam

Item number	Package size
M00322	1 Gallon
M00320	5 Gallon
M00323	55 Gallon



## MF200 Liquid Flux

### General Purpose - Lead-Free Compatible

DESCRIPTION/APPLICATION	% SOLIDS	% HALIDES	ACID VALUE	IPC CLASS	APPLICATION
A general purpose halide-free flux with sustained activity to extend flux life in dual wave and Pb-free wave soldering applications. Suitable for spray flux application systems.	6.4	Zero	37	ORMO	Spray/Foam

Item number	Package size
M00490	1 Gallon
M00491	5 Gallon
M00492	55 Gallon



## MF300 VOC-free

### Clear Residue Resin Free

DESCRIPTION/APPLICATION	% SOLIDS	% HALIDES	ACID VALUE	IPC CLASS	APPLICATION
General purpose VOC-free (water based), no-clean, halide-free and resin-free flux with special formulation to minimize solder balling. Compatible with Pb-free processes.	4.6	Zero	48.5	ORMO	Spray/Foam

Item number	Package size
M00469	1 Gallon
M00470	5 Gallon
M00471	55 Gallon



## MFR301

### IPA Based Rosin Flux

DESCRIPTION/APPLICATION	% SOLIDS	% HALIDES	ACID VALUE	IPC CLASS	APPLICATION
Higher solids flux for better wetting on reduced solderability surfaces and to minimize bridging on complex geometries. Fully Pb-free and dual wave compatible.	6.5	Zero	41	ROMO	Spray/Foam

Item number	Package size
M00472	1 Gallon
M00473	5 Gallon
M00474	55 Gallon

# Multicore® No-Clean VOC-Free Fluxes



**MF101 Liquid Flux**

**No Clean - VOC Free - Rosin Based Emulsion**

DESCRIPTION/APPLICATION	% SOLIDS	% HALIDES	ACID VALUE	IPC CLASS	APPLICATION
A unique <b>rosin emulsion</b> technology flux which combines the benefits of a <b>VOC-free</b> flux with the sustained activity of rosin. This can be used in <b>dual wave</b> applications for soldering bottom side SMD components. Excellent activity produces a wide process window reducing defects and improving hole-fill. <b>Can be used in lead-free wave applications.</b>	6.5 - 7.0	Zero	40	ROMO	Spray

Item number	Package size
M00372	1 Gallon
M00373	5 Gallon

# Multicore® Water Wash Fluxes - IPA Based

**Hydro-X/20**

**High Activity Flux**

DESCRIPTION/APPLICATION	% SOLIDS	% HALIDES	ACID VALUE	APPLICATION
A high activity <b>water washable</b> flux designed for the soldering of the most difficult electronic assemblies. Unique activator package enables a wider process window and the soldering of all common electronic surfaces with ease. Residues are readily and completely removed by water wash after soldering. <b>Suitable for lead-free wave soldering.</b>	20	1.0	24	Spray/Foam

Item number	Package size
M00274	1 Gallon
M00272	5 Gallon
M00273	55 Gallon

# Multicore® Cored Wire

The Multicore® line of cored wire features the renowned multiple flux cores technology to ensure even and consistent distribution of flux throughout the solder wire. This reliability makes multicore solder wire the first choice for automated wire soldering processes.

ITEM	DESCRIPTION	HALIDE CONTENT	IPC CLASS	ALLOY OPTIONS (Sn/Pb)	ALLOY OPTIONS (Pb-FREE)	CONTENT (BY WEIGHT)*
X39	Halide free, no-clean, clear residues	Zero	ROLO	60/40, 63/37, SN62	96SC, 99C	1%
400	Halide free, no-clean, clear residue, increased flux content for improved wetting.	Zero	ROLO	60/40, 63/37, SN62	96SC, 99C	2.2%
502	No-clean, clear residue, minimal activation for increased wetting speed.	0.2%	ROM1	60/40, 63/37, SN62	96SC, 99C	3%
309	General purpose high activity for fast wetting.	<1%	ROM1	60/40, 63/37, SN62	96SC, 99C	3%
Hydro-X	High activity water washable.	3%	ORH1	60/40, 63/37, SN62	96SC, 99C	2%

\*Flux content is nominal and may vary regionally due to market requirements. Please check with your regional supplier.

# Multicore® Cleaners



## Prozone SC01

### DESCRIPTION/APPLICATION

Prozone SC01 is designed for the stencil cleaning and hand cleaning of process soldering residues. A highly effective cleaner that dries rapidly (fast evaporation).

Item number	Package size
M00290	1 Gallon
M00297	5 Gallon
M00296	55 Gallon

## Other Multicore® Product Offerings

### Solder Mask

Temporary solder resists used with circuit boards prior to soldering. Will withstand flux and wave soldering operations. Suitable for use with copper, hand, robotic, pneumatic or template screening applications and brush.

Item number	Description	Package size
M292961	Spot-On Solder Mask	250 ml
M292967	Spot-On Solder Mask	5 liters

### Mini Fluxers and Cleaners

*Perfect for SMT re-work*

Controlled release flux and cleaner pen applicators. Range of compatible flux types available. Ideal for controlled application of flux when carrying out SMT re-work. Cleaner pen easily removes residues.

Item number	Description
M00385	MF-X33-04 No-Clean
M293319	MF-X33S-07i No-Clean
M00387	MF-638125 RMA Type
M293321	MF-Prozone Cleaner

### No-Clean Desoldering Wicks

Item number	Description	Length	Width
M293366	NCAA	5 ft. (1.524m)	1.5 mm (0.06in.)
M290996	NCAA	10 ft.(3.048m)	1.5 mm (0.06 in.)
M00390	NCAA	100 ft.(30.48 m)	1.5 mm (0.06 in.)
M290998	NCAB	5 ft.(1.524m)	2.2 mm (0.08 in.)
M291001	NCAB	100 ft.(3.048m)	2.2 mm (0.08 in.)
M291005	NCBB	5 ft.(1.524m)	2.7 mm (0.10 in.)
M291008	NCBB	10 ft.(30.48m)	2.7 mm (0.10 in.)
M00393	NCBB	100 ft.(30.48 m)	2.7 mm (0.10 in.)
M291013	NC00	5 ft.(1.524m)	0.8 mm (0.03 in.)
M291017	NC00	10 ft.(3.048m)	0.8 mm (0.03 in.)

### Tip Tinner

*Extends solder iron tip life*

Handy, non-abrasive solder iron tip-tinner. Easily wets hot solder irons leaving a brightly tinned tip. Improves hand soldering efficiency and extends tip life. Adhesive pad allows easy mounting on or near the solder iron holder.

Item number	Description
M293011	Tip-Tinner